Inventor: Chao-Yuan Su Serial No.: 10/051,906 Filed: Jan. 16, 2002

For: Method of Forming a Solder Ball Using ... Protective Layer Client Doc. No.: 67,200-630

Replacement Sheet

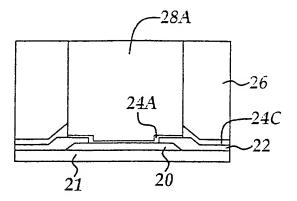


Figure 3A

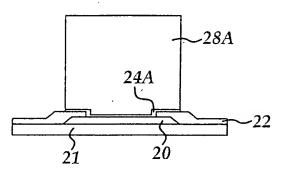


Figure 3B

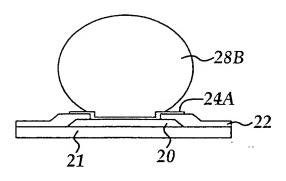


Figure 3C